

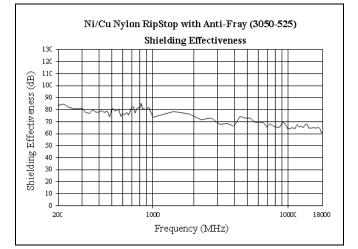
## Nickel/Copper Nylon Ripstop With Conductive Adhesive

Flectron® Nickel/Copper Nylon Ripstop with Conductive Adhesive is a unique fabric, manufactured using a patented, proprietary technology. Nylon Ripstop fabric is plated with highly conductive copper and corrosion resistant nickel. An anti-fray coating is applied to the fabric, then a conductive pressure sensitive adhesive (CPSA) is laminated to one side.

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Physical Properties				
Property	<u>Units</u>	Value	Advantage	
Substrate		Nylon Ripstop	Strong, Flexible, Conformable	
Metal		Ni/Cu	Highly Conductive, Corrosion Resistant	
Weight	oz./yd. <sup>2</sup> g/m. <sup>2</sup>	2.3 – 3.0 78 – 119	Light Weight	
Thickness, (nominal)	Inches microns	0.006 152	Thin and Flexible	
Max Short Duration Temperature		200°C	Allows Thermal Processing	

## Product No: 3050-532



## **Electrical Properties**

<b>Property</b>	<u>Units</u>	<u>Value</u>
Surface Resistivity (ASTM F390)	ohms/square	<u>&lt;</u> 0.07
Far-field Shielding	Effectiveness	(typical)
200 MHz to 18 GHz	dB	>60

## Mechanical Properties

<b>Property</b>	<u>Units</u>	<u>Value</u>
Tensile Strength, MD* (ASTM D5035)	Lb./in	50
180° Peel Strength (ASTM D3330)	oz/inch width	30

\* Machine Direction

FLECTRON® Nickel/Copper Nylon Ripstop with CPSA can be used in many different configurations to protect against EMI/RFI and ESD in a variety of applications. Typical applications include: enclosures, cables, tapes, and grounding.

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